

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Qing Ma
Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER STRUCTURE

Docket No.: 884.803US2
Filed: February 9, 2004
Examiner: Roy K. Potter

Serial No.: 10/774,923
Due Date: April 13, 2005
Group Art Unit: 2822

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response Under 37 C.F.R. 1.111 (10 Pages).

If not provided for in a separate paper filed herewith, Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

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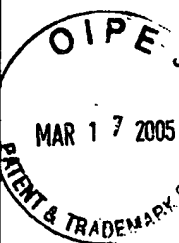
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 14th day of March, 2005.

Dennis J. Kempf
Name

[Signature]
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)

IFW



S/N 10/774,923

PATENT

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Applicant:	Qing Ma	Examiner:	Roy K. Potter
Serial No.:	10/774,923	Group Art Unit:	2822
Filed:	February 9, 2004	Docket No.:	884.803US2
Title:	DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER STRUCTURE		
Assignee:	Intel Corporation	Customer No:	21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
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PRELIMINARY REMARKS

Applicant gratefully acknowledges the provisional indication of allowability of several of the claims.

This responds to the Office Action mailed on January 13, 2005. Please amend the above-identified patent application as follows.